REMARKS

1.Present Status of the Application

Upon this response, claims 231-319 remain pending in the present application. More specifically, claims 231-319 are newly added; claims 1-230 are canceled. It is believed that the foregoing amendments add no new matter to the present application.

2.Response To Rejections

All pending claims 1, 6-9, 13-17, 25-29, 176-177, 180, 186-189, 193-196, 200, and 202-230 are rejected under 35 U.S.C. 102 or 103.

In this response, Applicants canceled claims 1, 6-9, 13-17, 25-29, 176-177, 180, 186-189, 193-196, 200, and 202-230, and added new claims 231-319.

Applicants respectfully traverse the rejections for at least the reasons set forth below.

Claim 231

As amended, independent claim 231 is recited below:

231. An electric component comprising:

a die having a top surface at a horizontal level;

a bottommost metal layer over said horizontal level and extending to a place not over said die, wherein said bottommost metal layer is connected to said die; and

a passive device over said horizontal level.

Applicants respectfully assert that the electric component claimed in claim 231 patentably distinguishes over the citations by Saia (US5,874,770) and by Eichelberger (US6,159,767).

Saia et al. teaches that a die 44 has a top surface at a horizontal level, a bottommost metal layer 38 is over the horizontal level and extends to a place not over the die 44, and a passive

device 28, 33 or 37 is over the horizontal level. ~ *See FIGS. 1-12* ~ Saia et al. teaches that vias 47 are formed in insulation layers 40, 10 and 42 and connects the third metal layer, not the bottommost metal layer 38, and the die 44. However, Saia et al. fails to teach, hint or suggest that the bottommost metal layer 38 can be connected to the die 44, which is claimed in claim 231.

Eichelberger teaches that a die 102 has a top surface at a horizontal level, and a bottommost metal layer 110 is over the horizontal level and extends to a place not over the die 102, wherein the bottommost metal layer 110 is connected to the die 102. ~ *See FIGS. 5A-5H* ~ Eichelberger teaches that the die 102 can be an integrated circuit chip, capacitor chip or resistor chip. ~ *See lines 66-1, cols. 8-9* ~ However, Eichelberger fails to teach, hint or suggest that a passive device can be deposited over the horizontal level, which is claimed in claim 231.

For at least the foregoing reasons, applicants respectfully submit independent claim 231 patently defines over the prior art references, and should be allowed. For at least the same reasons, dependent claims 232-279 patently define over the prior art as well.

Claim 280

As amended, independent claim 280 is recited below:

280. An electric component comprising:
a substrate comprising metal;
a die joined with said substrate, said die having a top surface at a horizontal level, wherein said substrate is under said horizontal level; and
a passive device over said horizontal level.

Applicants respectfully assert that the electric component claimed in claim 280 patentably distinguishes over the citations by Saia (US5,874,770) and by Eichelberger (US6,159,767).

Saia et al. teaches that a die 44 is joined with a substrate 45. The die 44 has a top surface at a horizontal level, wherein the substrate 45 is under the horizontal level. A passive device 28, 33 or 37 is over the horizontal level. ~ *See FIGS. 1-12* ~ Saia et al. teaches that the substrate 45 may comprises an epoxy molding compound. ~ *See lines 24-38, col.7* ~ However, Saia et al. fails to teach, hint or suggest that the substrate 45 may comprises metal, which is claimed in claim 280.

Eichelberger teaches that a die 102 is joined with a substrate 140. The die 102 has a top surface at a horizontal level, wherein the substrate 140 is under the horizontal level. ~ *See FIGS. 5e and 5f* ~ Eichelberger teaches that the die 102 can be an integrated circuit chip, capacitor chip or resistor chip. ~ *See lines 66-1, cols. 8-9* ~ However, Eichelberger fails to teach, hint or suggest that a passive device can be deposited over the horizontal level, which is claimed in claim 280. Moreover, Eichelberger fails to teach, hint or suggest that the substrate 140 may comprise metal, which is claimed in claim 280. Even though teaching that the die 102 can be joined with a heat sink, Eichelberger fails to teach, hint or suggest that the heat sink may comprise metal. ~ *See FIG. 4 and lines 16-18, col. 9* ~ Applicants consider that two features that "a passive device is deposited over the horizontal level" and "the substrate comprises metal" are not taught by Eichelberger.

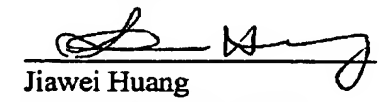
For at least the foregoing reasons, applicants respectfully submit independent claim 280 patently defines over the prior art references, and should be allowed. For at least the same reasons, dependent claims 281-319 patently define over the prior art as well.

CONCLUSION

For at least the foregoing reasons, it is believed that the pending claims 231-319 are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Respectfully submitted,
J.C. PATENTS

Date: 7/25/2005



Jiawei Huang
Registration No. 43,330

4 Venture, Suite 250
Irvine, CA 92618
Tel.: (949) 660-0761
Fax: (949)-660-0809